

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	26	(heat near sink) and (semiconductor or die or wafer) and lead\$2 and electrical\$4 and ground and wire and encapsulant and polyimide	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 12:08
S2	24	(heat near sink) and (semiconductor or die or wafer) and lead\$2 and electrical\$4 and ground and wire and encapsulant and polyimide and insulat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 12:08
S3	24	(heat near sink) and (semiconductor or die or wafer) and lead\$2 and electrical\$4 and ground and wire and encapsulant and polyimide and insulat\$4 and plat\$4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/19 12:09
S4	24	(heat near sink) and (semiconductor or die or wafer) and lead\$2 and electrical\$4 and ground and wire and encapsulant and polyimide and insulat\$4 and plat\$4 and package	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 10:58
S5	0	(heat near sink) and (semiconductor or die or wafer) and lead\$2 and electrical\$4 and (ground near wire) and encapsula\$8 and polyimide and insulat\$4 and plat\$4 and package	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/20 11:56
S6	17	(heat near sink) and (semiconductor or die or wafer) and lead\$2 and electrical\$4 and ground and wire and encapsulant and polyimide and insulat\$4 and plat\$4 and package and ring	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/23 10:58